We, CHI MEI CORPORATION, to the best of our knowledge hereby certify that the resins listed below (hereinafter referred as "products") as directly manufactured by us

**POLYLAC® ABS (J01)**

(J01) - The suffix may be used to denote the black color grade manufactured from Chi Mei Corp.
(A01 & A03) - The suffix may be used to denote the white color grade manufactured from Chi Mei Corp.

**POLYLAC® MABS**
- PA-758, PA-758R, LS-L230

**KIBISAN® SAN**

**POLYREX® PS**

**ACRYREX® PMMA**

**ACRYSTEX® SMMA**
- PM-600, PM-500, PM-500G, PM-500X

**KIBITON® TPE**
- PB-575, PB-585, PB-511, PB-5300, PB-5301, PB-5302, PB-5308, PB-5502

**KIBITON® Q-resin**
- PB-5903, PB-5910, PB-5925, PB-5900, PB-5630, PB-5906

**KIBIPOL® LBR/SSBR/HBR**
- PR-245, PR-255, PR-1205, PR-110, PR-040, PR-040S, PR-040G, PR-040C

**ACRYPOLY®**
- CM-205X, CM-205B

**KIBILITE®**

**KIBILAC®**

contain no following substances.

1. Halogen (F, Br, I) and its compounds
2. Halogen (CI)
3. PBDEs (Polybrominated Diphenyl Ethers)
4. PBBS (Polybrominated Biphenyls)
5. Ozone Depleting Chemicals (CFCs & HCFCs)
6. Chlorinated Paraffin (C10-C13)
7. Polyvinyl Chloride (PVC)
8. Mercury (Hg) and its compounds
9. Lead (Pb) and its compounds
10. Cadmium (Cd) and its compounds
11. Chromium (Cr) and its compounds
12. Arsenic (As) and its compounds
13. Antimony (Sb) and its compounds
14. Selenium (Se) and its compounds
15. Barium (Ba) and its compounds

25. 2-(2'-Hydroxy-3',5'-di-tert-butylphenyl)benzotriazole
26. PFOA, PFOS
27. Bisphenol A
28. Formaldehyde
29. Dimethylfumarate (DMF)
30. Triclosan
31. Nickel
32. REACH- Candidate List of SVHC
33. Radioactive Substances
34. Natural Latex
35. Dioxins and furans
36. Primary aromatic amines (PAA)
37. Perchlorate
38. Hexachlorobenzene
39. Mirex

The above statement is based on our current level of knowledge and covers the above products directly manufactured and supplied by CHI MEI CORPORATION at the date of issue. CHI MEI CORPORATION makes no warranties, whether express or implied, and assumes no liability in connection with any use of above information. Notwithstanding the foregoing, CHI MEI CORPORATION shall in no event be held obligated or liable for any claims due to or arising from (i) any customer provided, consigned, materials and/or parts, which are incorporated or adopted in the products; (ii) any combination of the products with material not provided or authorized by our company; (iii) any modifications to the products which are made or directed by customer; (iv) our compliance with the specifications, instructions, and/or designs provided by customer; (v) any anti-trust, unfair competition and/or other unlawful actions effected by customer; or (vi) any defects, infringement, breach and/or violation which are arising out of customer's faults or otherwise not solely and directly attributable to CHI MEI CORPORATION. In no event will CHI MEI CORPORATION be liable for any indirect, special, exemplary, punitive, or consequential damages (including lost profits) of any nature whatsoever whether arising out of the purchase, shipment, unloading, handling, or use of any product or otherwise.
16. Beryllium (Be) and its compounds
17. Bismuth (Bi) and its compounds
18. Organic tin compounds (TBT, TPT, DOT, DBT)
19. Polychlorinated Biphenyls (PCBs) and Terphenyls (PCTs) and Naphtalenes (PCNs)
20. Poly naphthalenes
21. Azo colorants (according to REACH-ANNEX-XVII-APPENDIX 8)
22. Asbestos
23. Phthalates
24. APEO: Including Alkylphenol(AP), Octylphenol(OP), Nonylphenol(NP), Octylphenol ethoxylates(OPE), Nonylphenol ethoxylates(NPE)

40. Specified amine compounds
41. Benzene
42. Benzenamine, N-phenyl-, Reaction Products with Styrene and 2,4,4-Trimethylpentene (BNST)
43. Polyamide
44. PVDC (polyvinylidene chloride)
45. ESBO (Expoxidized soybean oil)
46. Formamide
47. Hexabromocyclododecane (HBCDD)
48. Red phosphorus
49. Aniline • formaldehyde polycondensate
50. Fluorescent powder
51. 4,4’-Sulfonylediphenol (BPS)

With regard to composition of above grades of products, the aforesaid products comply with the Directives of RoHS (2011/65/EU), 2003/11/EC, TCO’07, Blue Angel and SONY Standard (SS-00259).

Sincerely Yours,

Perry D. B. Shiueh

Vice President of R&D Division

The above statement is based on our current level of knowledge and covers the above products directly manufactured and supplied by CHI MEI CORPORATION at the date of issue. CHI MEI CORPORATION makes no warranties, whether express or implied, and assumes no liability in connection with any use of above information. Notwithstanding the foregoing, CHI MEI CORPORATION shall in no event be held obligated or liable for any claims due to or arising from (i) any customer provided, consigned, materials and/or parts, which are incorporated or adopted in the products; (ii) any combination of the products with material not provided or authorized by our company; (iii) any modifications to the products which are made or directed by customer; (iv) our compliance with the specifications, instructions, and/or designs provided by customer; (v) any anti-trust, unfair competition and/or other unlawful actions effected by customer; or (vi) any defects, infringement, breach and/or violation which are arising out of customer’s faults or otherwise not solely and directly attributable to CHI MEI CORPORATION. In no event will CHI MEI CORPORATION be liable for any indirect, special, exemplary, punitive, or consequential damages (including lost profits) of any nature whatsoever whether arising out of the purchase, shipment, unloading, handling, or use of any product or otherwise.